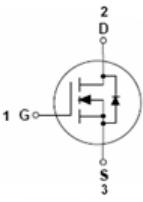
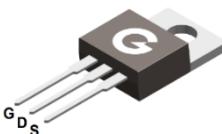


<p>Features</p> <ul style="list-style-type: none"> ● Advanced Trench technology ● Provide excellent $R_{DS(ON)}$ and low gate charge ● JEDEC22-A114-B ESD rating of class 1C per human body model <p>Mechanical Data</p> <ul style="list-style-type: none"> ● Case: TO-220AB ● Molding Compound: UL Flammability Classification Rating 94V-0 ● Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208 	HF	  TO-220AB
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Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL035N03	TO-220AB	50 pcs / Tube	035N03

Maximum Ratings (@ $T_c = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	30	V
Gate-to-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ($T_c = 25^\circ\text{C}$, Silicon Limited)	I_D	135	A
Continuous Drain Current ($T_c = 25^\circ\text{C}$, Package Limited)	I_D	80	A
Continuous Drain Current ($T_c = 100^\circ\text{C}$)	I_D	85	A
Pulsed Drain Current ($t_p = 10\mu\text{s}$, $T_c = 25^\circ\text{C}$)	I_{DM}	540	A
Single Pulse Avalanche Energy ^{*3}	E_{AS}	77	mJ

Thermal Characteristics

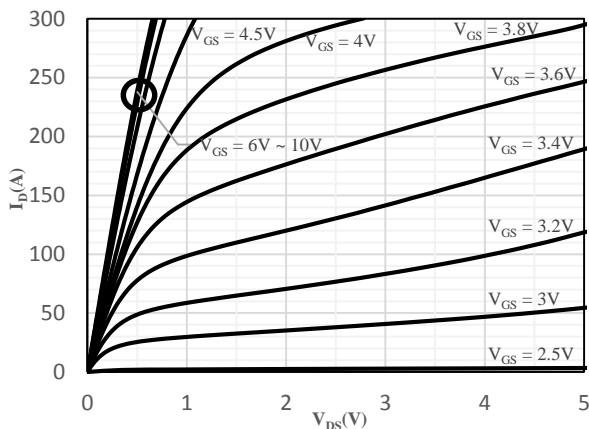
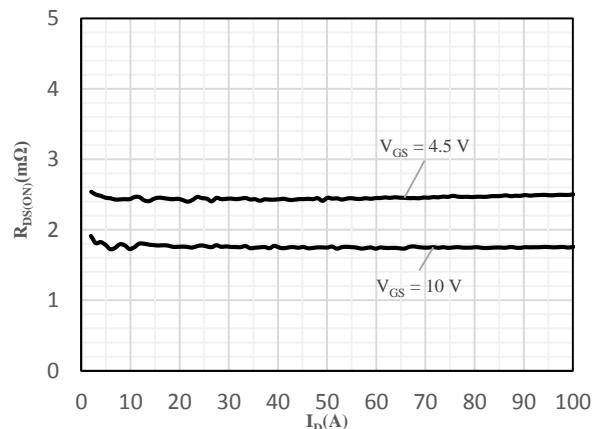
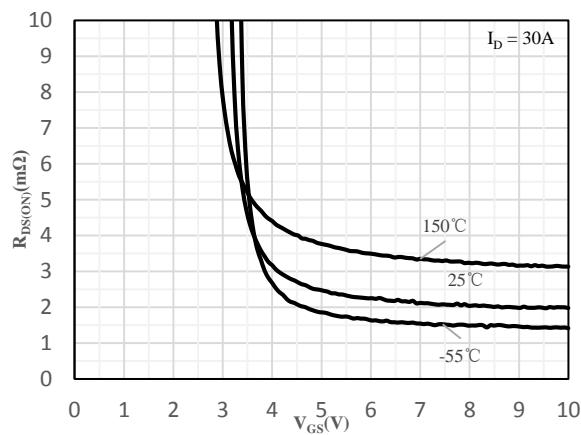
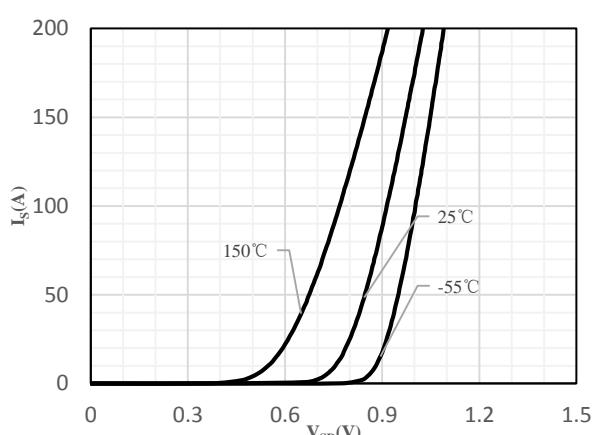
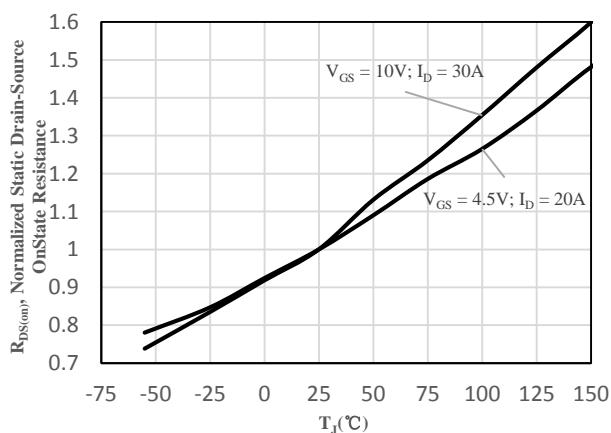
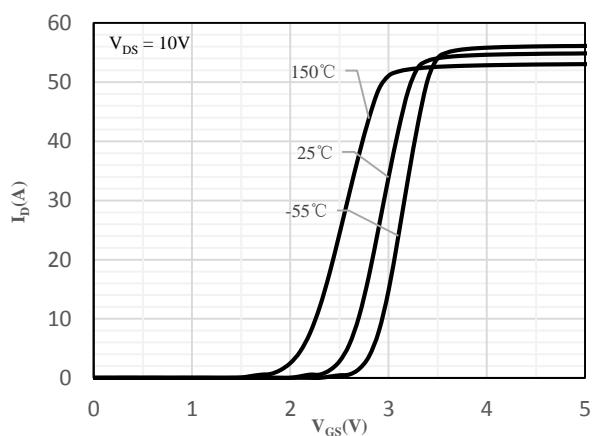
Parameter	Symbol	Value	Unit
Power Dissipation ($T_c = 25^\circ\text{C}$)	P_D	104	W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	1.2	°C/W
Thermal Resistance Junction-to-Air ^{*1}	$R_{\theta JA}$	50	°C/W
Operating Junction Temperature Range	T_J	-55 ~ +150	°C
Storage Temperature Range	T_{STG}	-55 ~ +150	°C

Electrical Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	30	-	-	V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	-	-	± 100	nA
On Characteristics						
$R_{DS(ON)}$	Static Drain-Source On-resistance * ²	$V_{GS} = 10\text{V}, I_D = 30\text{A}$	-	-	3.5	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 20\text{A}$	-	-	6.2	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.5	2.5	V
R_G	Gate Resistance	$V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	1.7	-	Ω
Dynamic Characteristics						
C_{ISS}	Input Capacitance	$V_{GS} = 0\text{V}$ $V_{DS} = 15\text{V}$ $f = 1.0\text{MHz}$	-	5102	-	pF
C_{OSS}	Output Capacitance		-	655	-	
C_{RSS}	Reverse Transfer Capacitance		-	551	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time * ⁴	$V_{DS} = 15\text{V}$ $R_G = 1.8\Omega$ $I_D = 60\text{A}$	-	11	-	ns
t_r	Turn-on Rise Time * ⁴		-	120	-	
$t_{d(OFF)}$	Turn-Off Delay Time * ⁴		-	25	-	
t_f	Turn-Off Fall Time * ⁴		-	60	-	
Q_G	Total Gate-Charge	$V_{DS} = 15\text{V}$ $V_{GS} = 10\text{V}$ $I_D = 30\text{A}$	-	98.7	-	nC
Q_{GS}	Gate to Source Charge		-	15	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	18.7	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage * ²	$I_{SD} = 20\text{A}, V_{GS} = 0\text{V}$	-	0.78	1.2	V
t_{rr}	Reverse Recovery Time	$I_F = 40\text{A}, V_{GS} = 0\text{V}$ $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	92	-	ns
Q_{rr}	Reverse Recovery Charge		-	80	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The E_{AS} data shows Max. rating. The test condition is $V_{DD} = 15\text{V}, V_{GS} = 10\text{V}, L = 0.5\text{mH}$
4. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Fig 1 Typical Output Characteristics

Fig 2 On-Resistance vs. Drain Current and Gate Voltage

Fig 3 On-Resistance vs. Gate-Source Voltage

Fig 4 Body-Diode Characteristics

Fig 5 Normalized On-Resistance vs. Junction Temperature

Fig 6 Transfer Characteristics

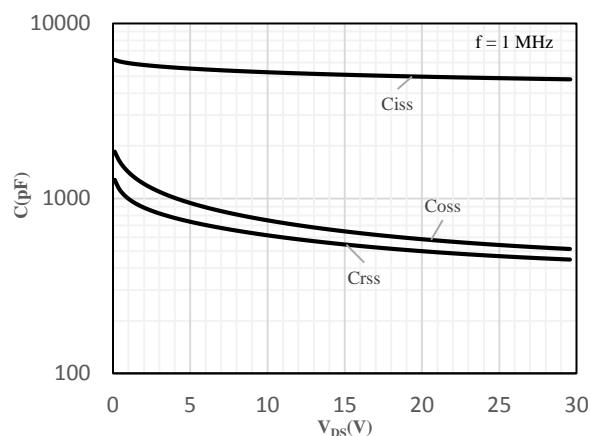


Fig 7 Capacitance Characteristics

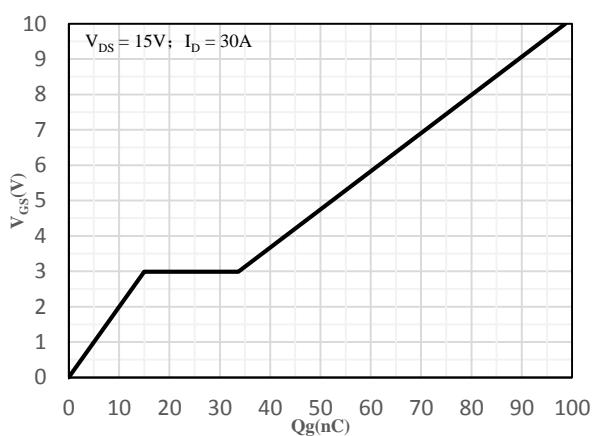


Fig 8 Gate-Charge Characteristics

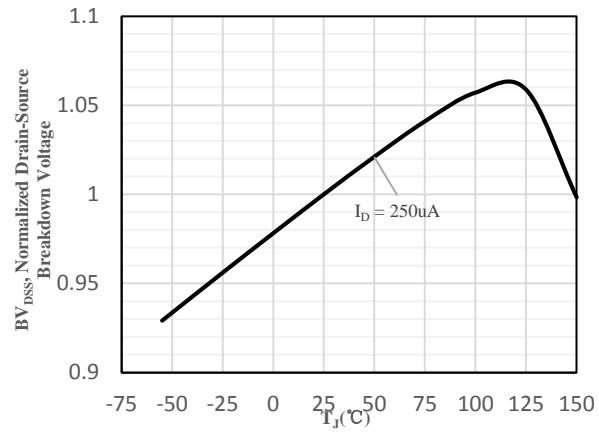


Fig 9 Normalized Breakdown Voltage
vs. Junction Temperature

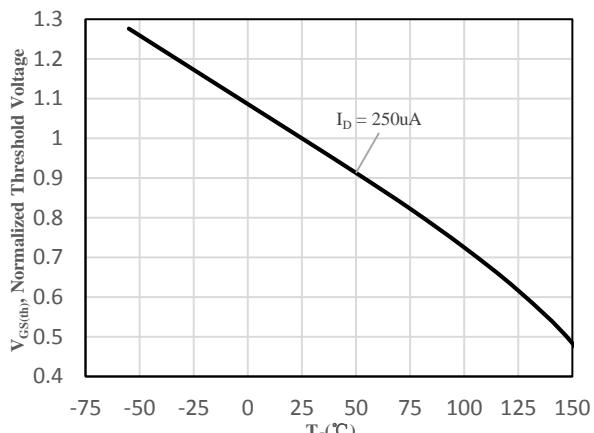
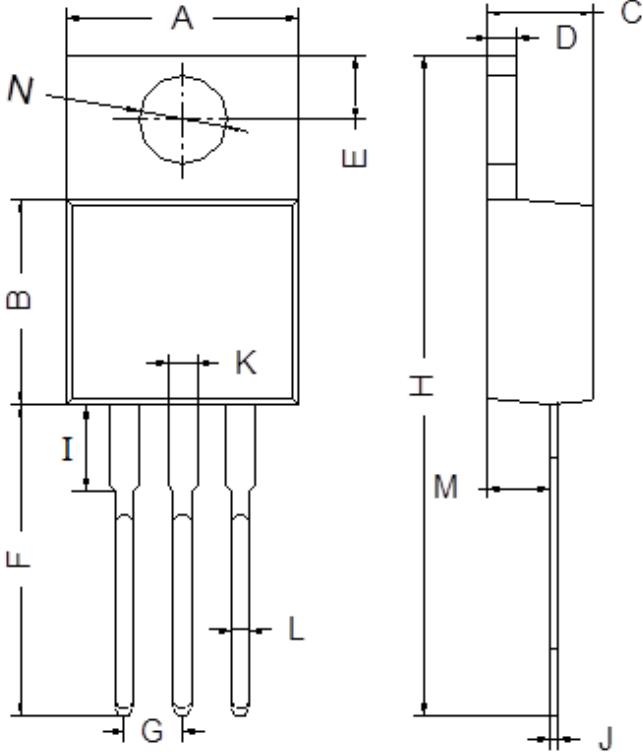


Fig 10 Normalized $V_{GS(th)}$ vs. Junction Temperature

Package Outline Dimensions (Unit: mm)



The diagram illustrates the TO-220AB package outline with various dimensions labeled:

- A:** Total width of the package body.
- B:** Total height of the package body.
- C:** Width of the lead foot.
- D:** Lead thickness.
- E:** Lead height.
- F:** Lead pitch.
- G:** Lead width.
- H:** Total height of the package including leads.
- I:** Lead thickness.
- J:** Lead width.
- K:** Lead pitch.
- L:** Lead height.
- M:** Lead thickness.
- N:** Lead width.
- W:** Lead thickness.

TO-220AB		
Dimension	Min.	Max.
A	9.80	10.30
B	8.70	9.10
C	4.37	4.77
D	1.07	1.47
E	2.64	2.84
F	13.14	13.74
G	2.44	2.64
H	28.03	28.83
I	3.50	4.00
J	0.28	0.48
K	1.22	1.32
L	0.71	0.91
M	2.40	2.60
N	3.76	3.96

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